

TM4618B

N+P-Channel Enhancement Mode Mosfet

General Description

- Low $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

Applications

- Load switch
- PWM

General Features

N Channel

$V_{DS} = 40V, I_D = 9A$
 $R_{DS(ON)} = 17m\Omega$ (typ.) @ $V_{GS} = 10V$

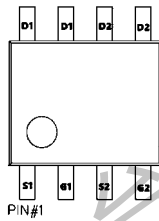
P Channel

$V_{DS} = -40V, I_D = -7A$
 $R_{DS(ON)} = 41m\Omega$ (typ.) @ $V_{GS} = -10V$

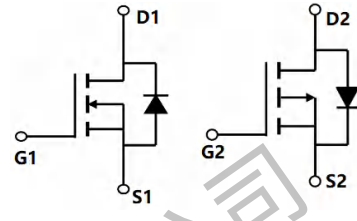
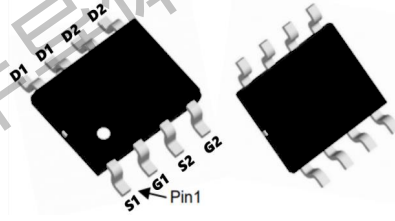
100% UIS Tested
100% R_g Tested



S:SOP-8L



Marking: TM46148B



Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating		Units
		N-Channel	P-Channel	
V_{DS}	Drain-Source Voltage	40	-40	V
V_{GS}	Gate-Source Voltage	± 20	± 20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	9	-7	A
$I_D @ T_A = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	5.2	-3.9	A
I_{DM}	Pulsed Drain Current ²	30	-23	A
EAS	Single Pulse Avalanche Energy ³	13	17.6	mJ
$P_D @ T_A = 25^\circ C$	Total Power Dissipation ⁴	2.0	3.2	W
T_{STG}	Storage Temperature Range	-55 to 175	-55 to 175	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 175	-55 to 175	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	85	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	62.5	$^\circ C/W$



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N-Channel Electrical Characteristics: ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV _{DSS}	Drain-Sourtce Breakdown Voltage	V _{GS} =0V, I _D =250 μ A	40	---	---	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} =0V, V _{DS} =40V	---	---	1	μ A
I _{GSS}	Gate-Source Leakage Current	V _{GS} =± 20V, V _{DS} =0A	---	---	± 100	nA
On Characteristics ³						
V _{GS(th)}	GATE-Source Threshold Voltage	V _{GS} =V _{DS} , I _D =250 μ A	1.2	1.6	2.0	V
R _{DS(ON)}	Drain-Source On Resistance ^{note3}	V _{GS} =10V, I _D =8A	---	17	22	m Ω
		V _{GS} =4.5V, I _D =5A	---	25	35	
Dynamic Characteristics ⁴						
C _{iss}	Input Capacitance	V _{DS} =20V, V _{GS} =0V, f=1MHz	---	620	---	pF
C _{oss}	Output Capacitance		---	65	---	
C _{rss}	Reverse Transfer Capacitance		---	55	---	
Q _g	Gate Charge	V _{GS} =8V V _{DS} =20V I _D =10A		12	---	nC
Q _{gs}	Gate-Source Charge			3.2	---	
Q _{gd}	Gate-Drain Charge			3.1	---	
Switching Characteristics ⁴						
t _{d(on)}	Turn-On Delay Time	V _{DS} =20V, R _L =2.5 Ω , R _{REN} =3 Ω ,V _{GS} =10V	---	4	---	ns
t _r	Rise Time		---	3	---	ns
t _{d(off)}	Turn-Off Delay Time		---	15	---	ns
t _f	Fall Time		---	2	---	ns
Drain-Source Diode Characteristics						
I _S	Continuous Drain to Source Diode	---	---	----	9	A
I _{SM}	Pulsed Drain to Source Diode	---	---	---	30	A
V _{SD}	Source-Drain Diode Forward Voltage	V _{GS} =0V, I _S =8A	---	---	1.2	V

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition : $T_J=25^\circ\text{C}, V_{DD}=20V, V_G=10V, L=0.5mH, R_g=25\Omega, I_{AS}=7.2A$
 $T_J=25^\circ\text{C}, V_{DD}=-20V, V_G=-10V, L=0.5mH, R_g=25\Omega, I_{AS}=-8.4A$
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

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Typical Performance Characteristics-N

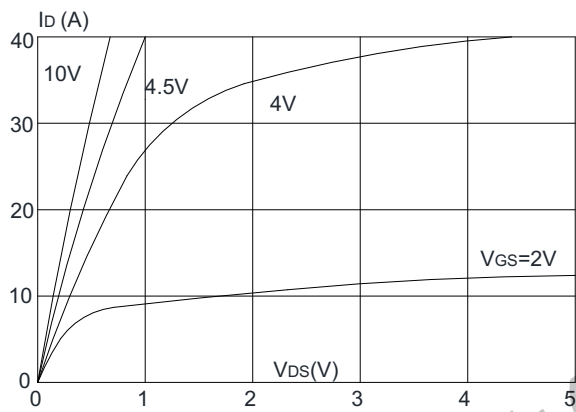


Figure1: Output Characteristics

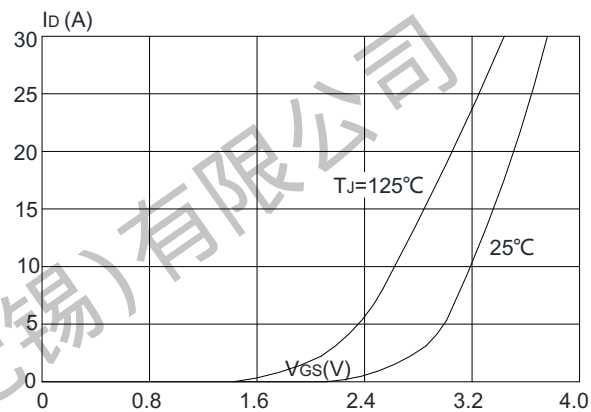


Figure 2: Typical Transfer Characteristics

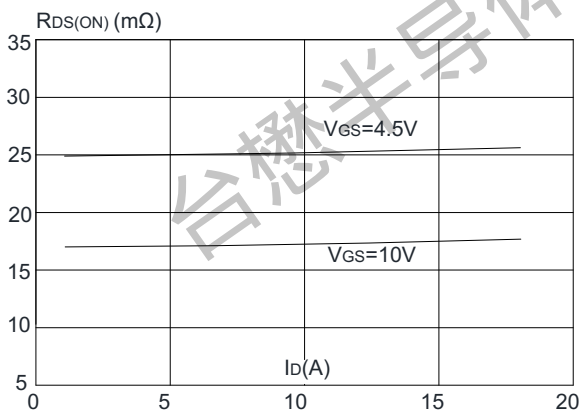


Figure 3: On-resistance vs. Drain Current

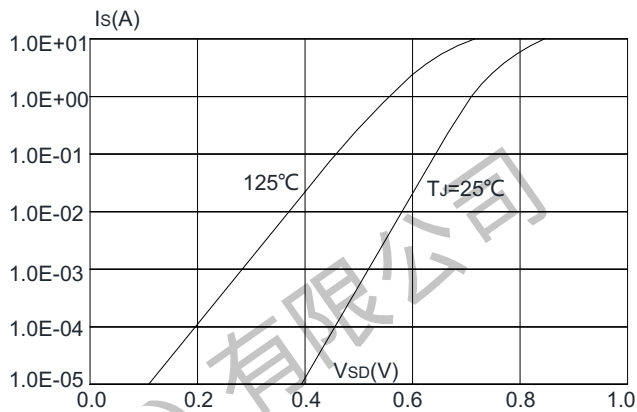


Figure 4: Body Diode Characteristics

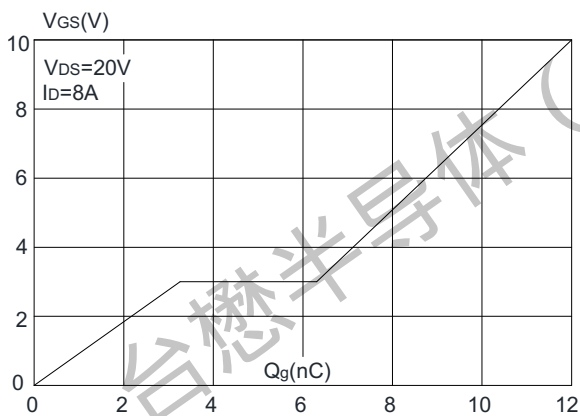


Figure 5: Gate Charge Characteristics

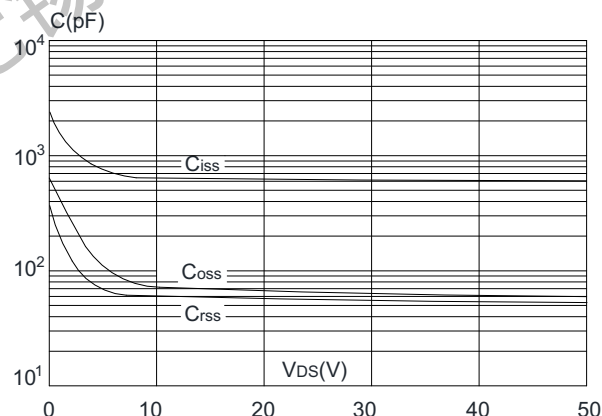


Figure 6: Capacitance Characteristics

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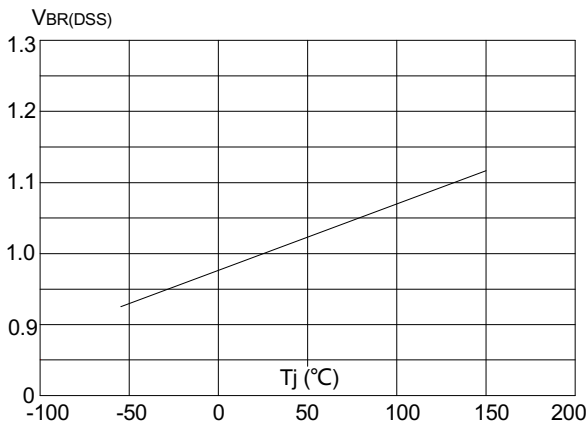


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

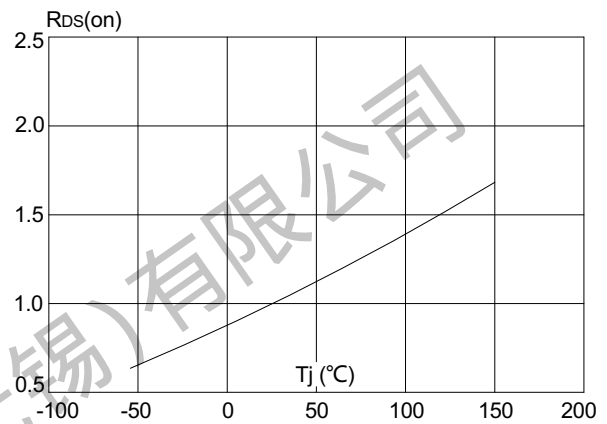


Figure 8: Normalized on Resistance vs. Junction Temperature

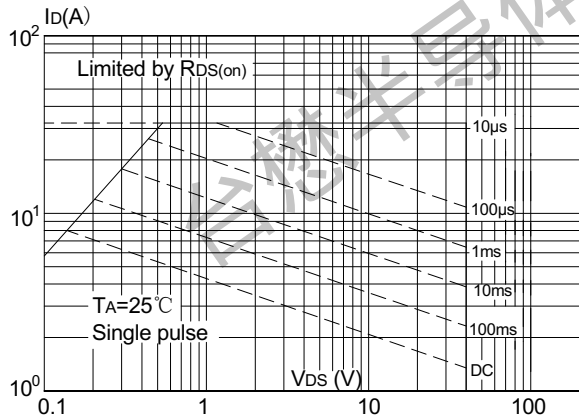


Figure 9: Maximum Safe Operating Area

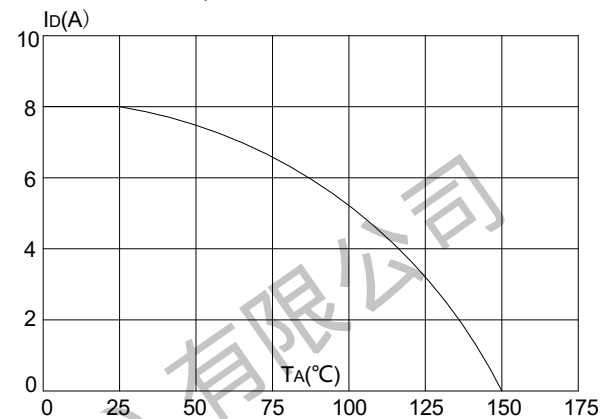


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

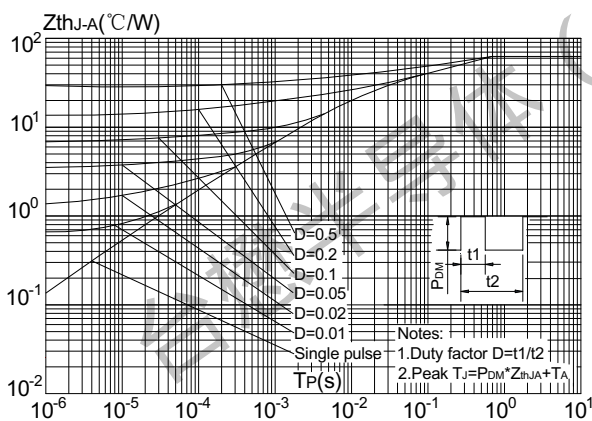


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



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P-Channel Electrical Characteristics: ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV _{DSS}	Drain-Sourtce Breakdown Voltage	V _{GS} =0V, I _D =250 μ A	-40	---	---	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} =0V, V _{DS} =-40V	---	---	-1	μ A
I _{GSS}	Gate-Source Leakage Current	V _{GS} =± 20V, V _{DS} =0A	---	---	± 100	nA
On Characteristics ³						
V _{GS(th)}	GATE-Source Threshold Voltage	V _{GS} =V _{DS} , I _D =250 μ A	-1	-1.75	-2.5	V
R _{DS(ON)}	Drain-Source On Resistance ^{note3}	V _{GS} =-10V, I _D =-6A	---	41	53	m Ω
		V _{GS} =-4.5V, I _D =-4A	---	58	75	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =-20V, V _{GS} =0V, f=1MHz	---	850	---	pF
C _{OSS}	Output Capacitance		---	85	---	
C _{rss}	Reverse Transfer Capacitance		---	68	---	
Switching Characteristics ⁴						
t _{d(on)}	Turn-On Delay Time	V _{DD} = -20V, R _L =2.3 Ω V _{GS} = -10V, R _{GEN} =6 Ω	---	7.5	---	ns
t _r	Rise Time		---	5.5	---	ns
t _{d(off)}	Turn-Off Delay Time		---	19	---	ns
t _f	Fall Time		---	7	---	ns
Q _g	Total Gate Charge	V _{GS} =-10V, V _{DS} =-20V, I _D =-6A	---	13	---	nC
Q _{gs}	Gate-Source Charge		---	3.8	---	nC
Q _{gd}	Gate-Drain “Miller” Charge		---	3.1	---	nC
Drain-Source Diode Characteristics						
I _S	Continuous Drain to Source Diode	---	---	---	-7	A
I _{SM}	Pulsed Drain to Source Diode	---	---	---	-23	---
V _{SD}	Source-Drain Diode Forward Voltage	V _{GS} =0V, I _S =-6A	---	---	-1.2	V

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Typical Performance Characteristics-P

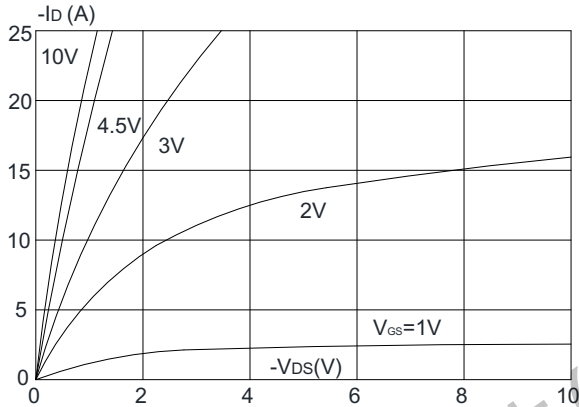


Figure 1: Output Characteristics

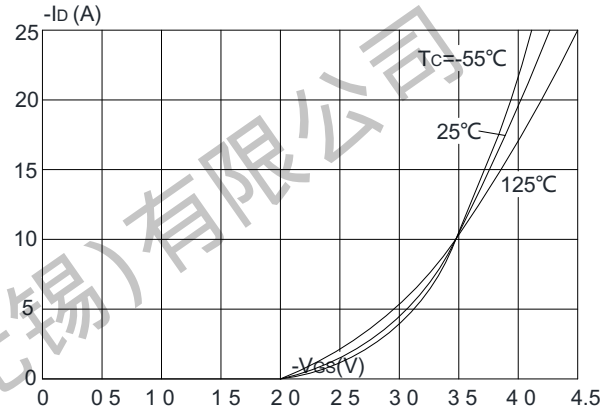


Figure 2: Typical Transfer Characteristics

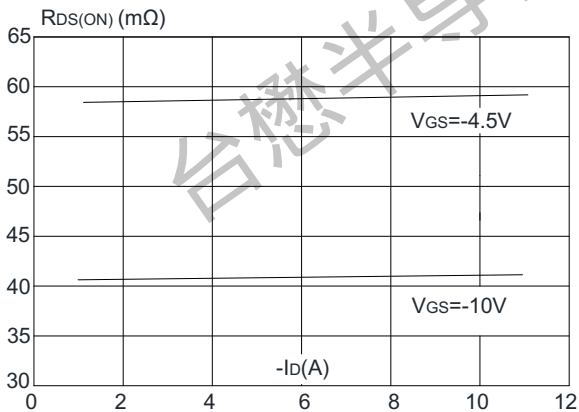


Figure 3: On-resistance vs. Drain Current
V (V)

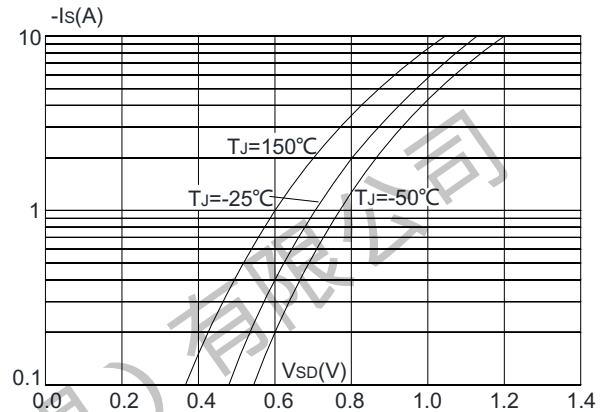


Figure 4: Body Diode Characteristics

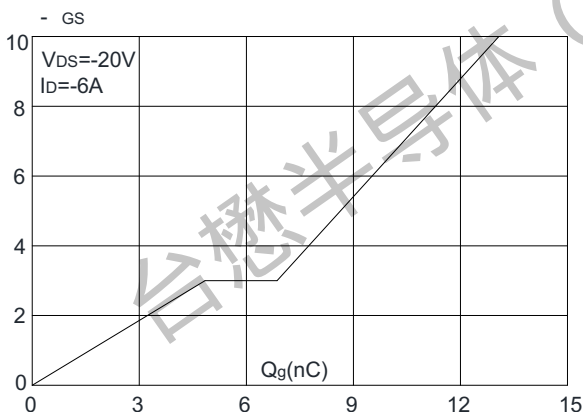


Figure 5: Gate Charge Characteristics

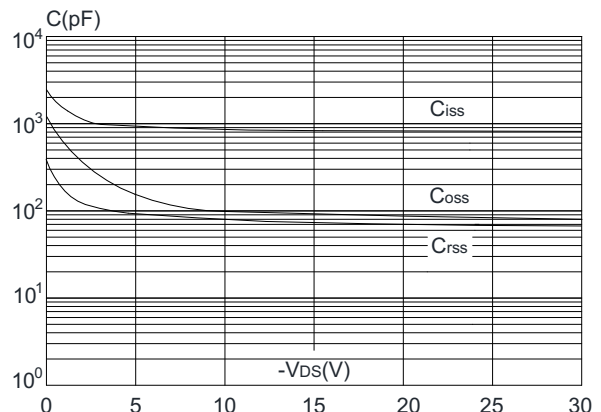


Figure 6: Capacitance Characteristics

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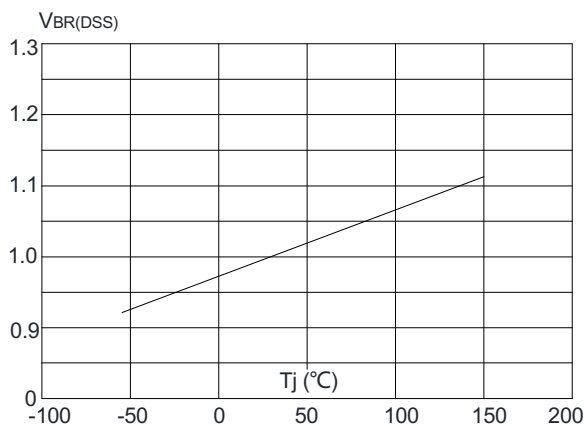


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

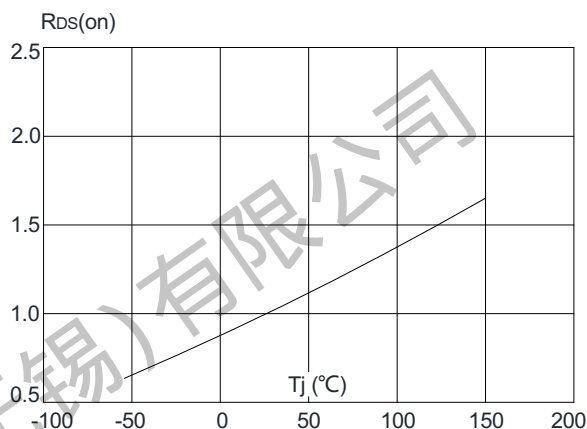


Figure 8: Normalized on Resistance vs. Junction Temperature

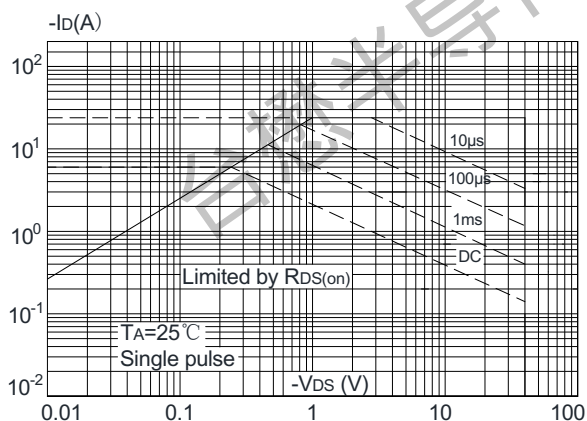


Figure 9: Maximum Safe Operating Area

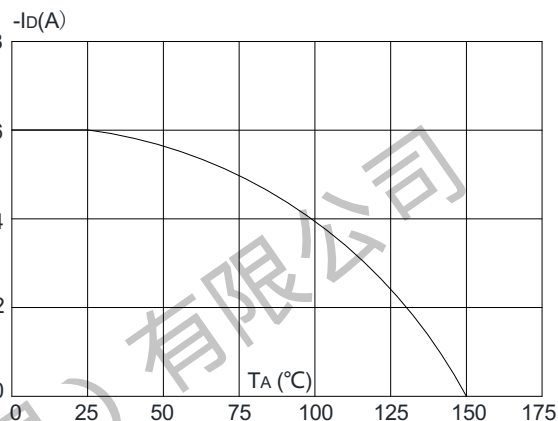


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

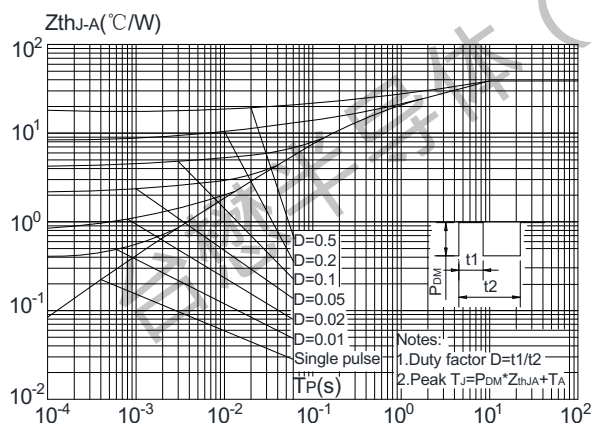
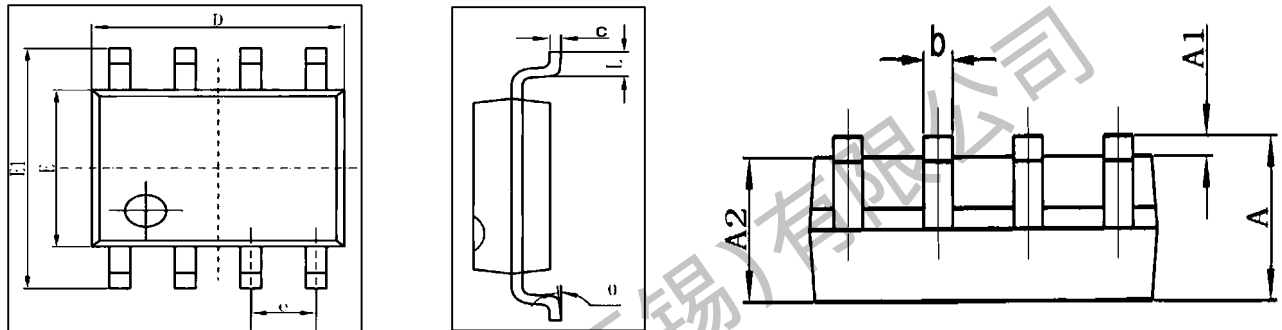


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

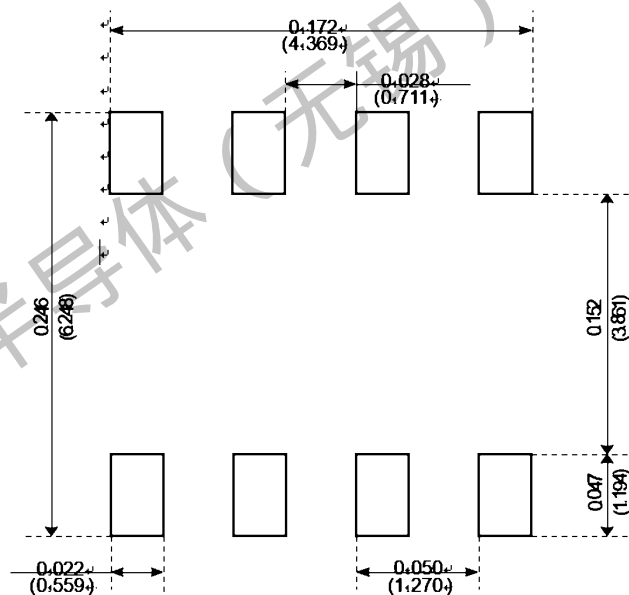
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Package Mechanical Data:SOP-8L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

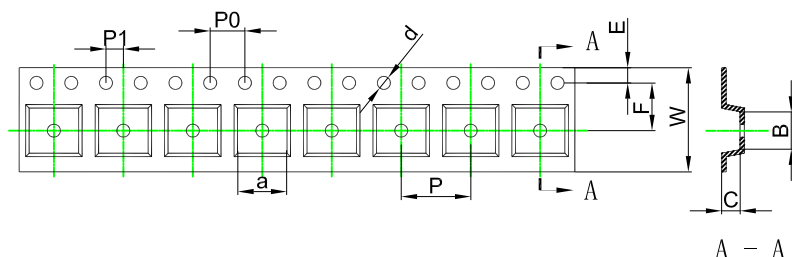


Recommended Minimum Pads

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SOP-8L Embossed Carrier Tape



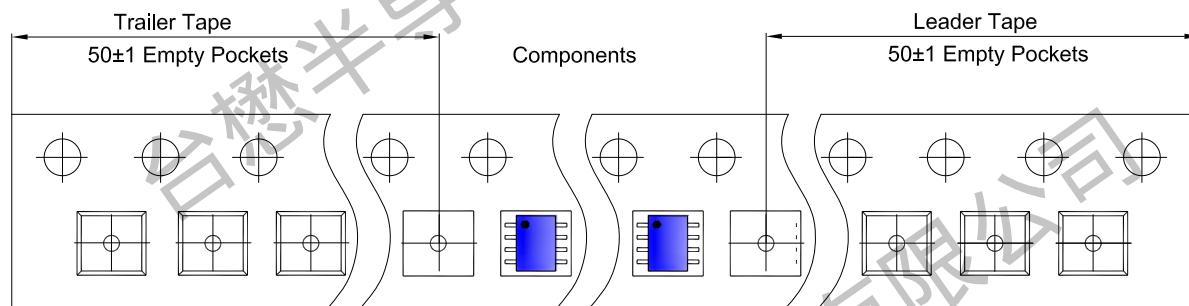
Packaging Description:

SOP-8L parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 2,500 units per 13" or 33cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).

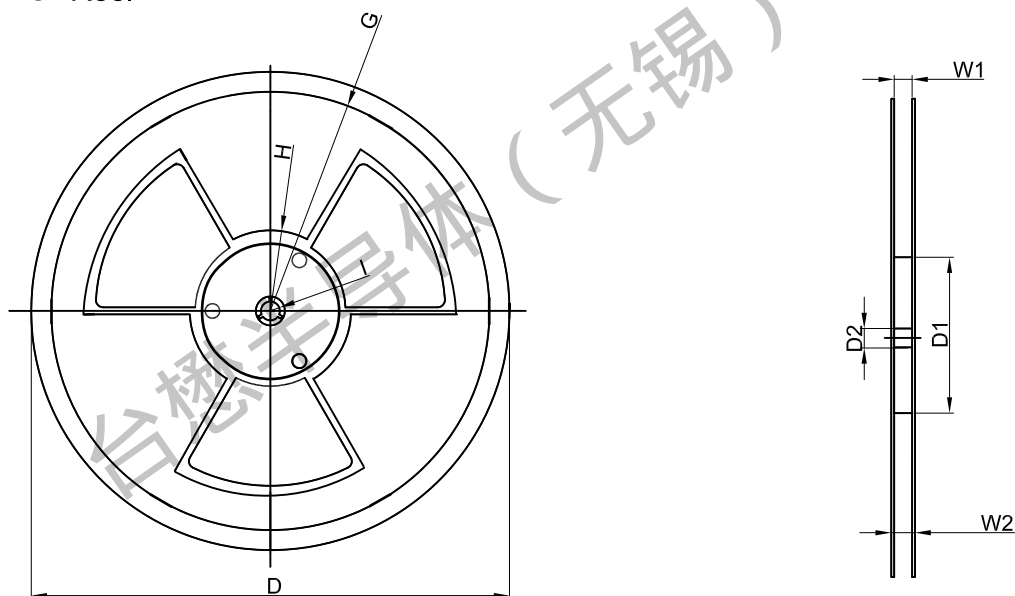
ALL DIM IN mm

Dimensions are in millimeter										
Pkg type	a	B	C	d	E	F	P0	P	P1	W
SOP-8L	6.40	5.40	2.10	Ø1.50	1.75	5.50	4.00	8.00	2.00	12.00

SOP-8L Tape Leader and Trailer



SOP-8L Reel



Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
13"Dia	Ø330.00	100.00	13.00	R135.00	R55.00	R6.50	12.00	14.00

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
3,000 pcs	13 inch	6,000 pcs	370×355×52	48,000 pcs	400×360×368	

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Revision history:

Date	Rev	Description	Page
2023.07.17	23.07	Original	